

2SJ244

Silicon P Channel MOS FET (DIII-L)

Application

High speed power switching
Low voltage operation

Features

- Very low on-resistance
- High speed switching
- Suitable for camera or VTR motor drive circuit, power switch, solenoid drive and etc.

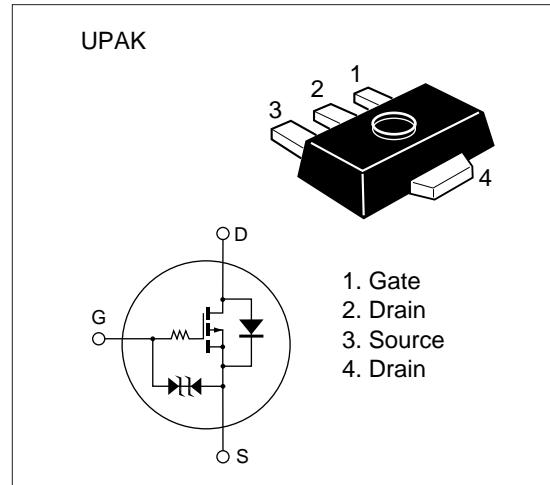


Table 1 Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-12	V
Gate to source voltage	V _{GSS}	±7	V
Drain current	I _D	±2	A
Drain peak current	I _{D(pulse)} *	±4	A
Channel dissipation	P _{ch} **	1	W
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

* PW < 100 µs, duty cycle < 10 %

** Value on the alumina ceramic board (12.5x20x0.7 mm)

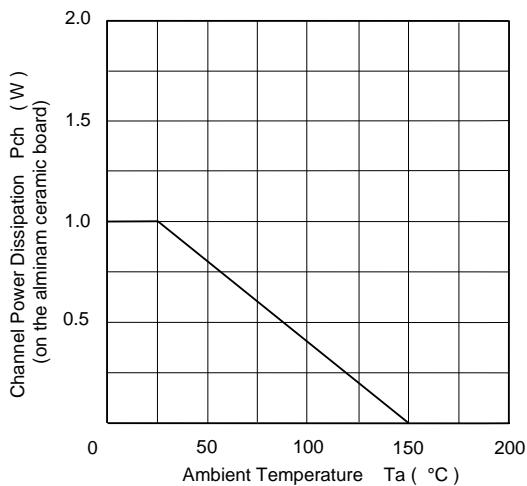
*** Marking is "JY".

Table 2 Electrical Characteristics (Ta = 25°C)

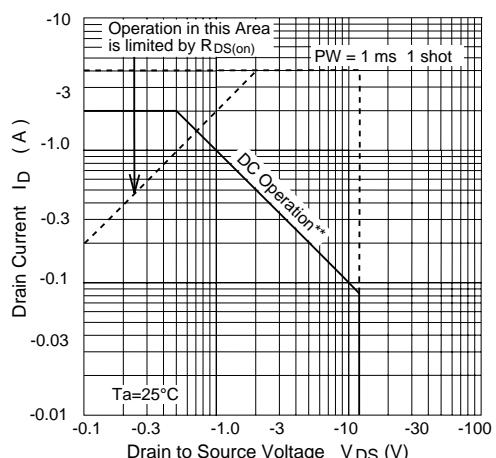
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-12	—	—	V	I _D = -1 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS}	±7	—	—	V	I _G = ±10 µA, V _{DS} = 0
Gate to source cutoff current	I _{GSS}	—	—	±5	µA	V _{GS} = ±6 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	-1	µA	V _{DS} = -8 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	-0.4	—	-1.4	V	I _D = -100 µA V _{DS} = -5 V
Static drain to source on state resistance	R _{DS(on)1}	—	0.65	0.9	Ω	I _D = -0.5 A * V _{GS} = -2.5 V
Static drain to source on state resistance	R _{DS(on)2}	—	0.5	—	Ω	I _D = -1 A * V _{GS} = -4 V
Forward transfer admittance	y _{fs}	—	1.8	—	S	I _D = -1 A * V _{DS} = -5 V
Input capacitance	C _{iss}	—	130	—	pF	V _{DS} = -5 V
Output capacitance	C _{oss}	—	50	—	pF	V _{GS} = 0
Reverse transfer capacitance	C _{rss}	—	260	—	pF	f = 1 MHz
Turn-on time	t _(on)	—	365	—	ns	I _D = -0.2 A*, Vin = -4 V
Turn-off delay time	t _(off)	—	1450	—	ns	R _L = 51 Ω
Body-drain diode forward voltage	V _{DF}	—	—	7	V	I _F = 4 A*, V _{GS} = 0

* Pulse Test

Maximum Channel Power Dissipation Curve

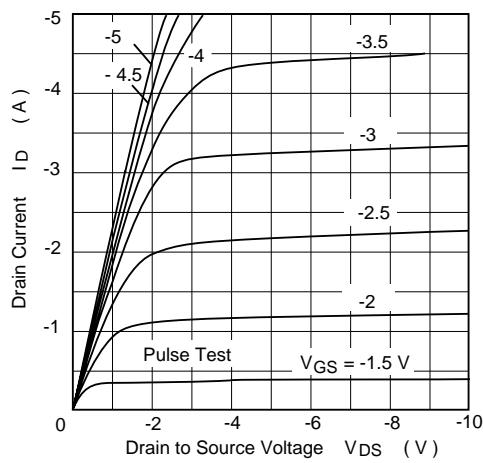


Safe Operation Area

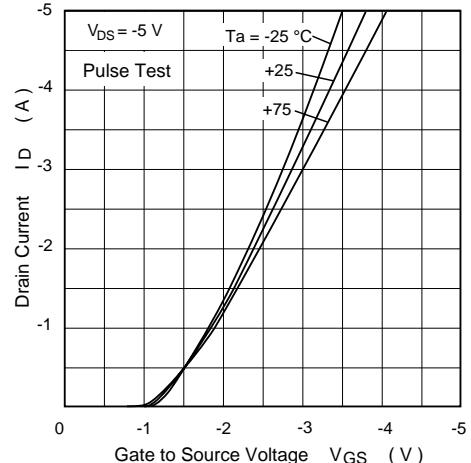


**ON the almina
ceramic board

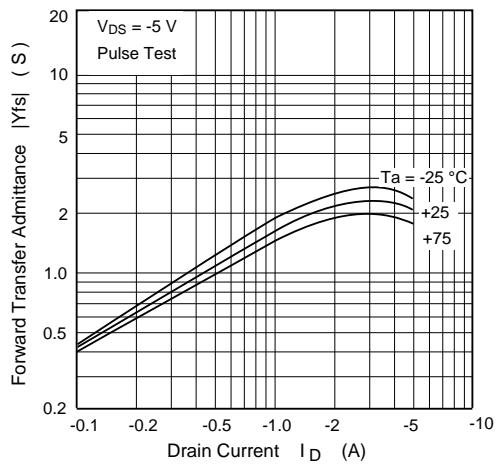
Typical Output Characteristics



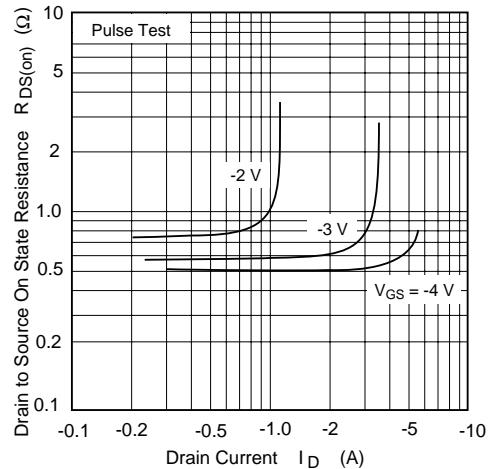
Typical Forward Transfer Characteristics



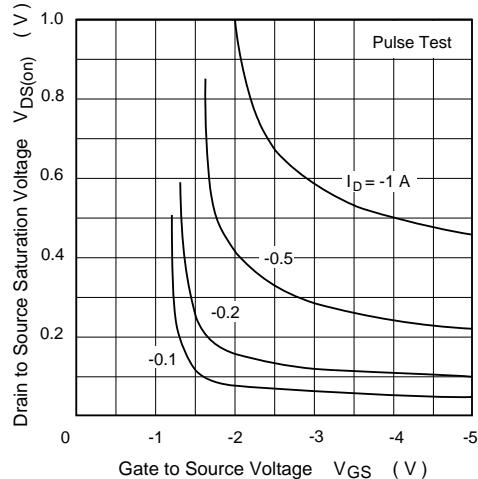
Forward Transfer Admittance vs.
Drain Current



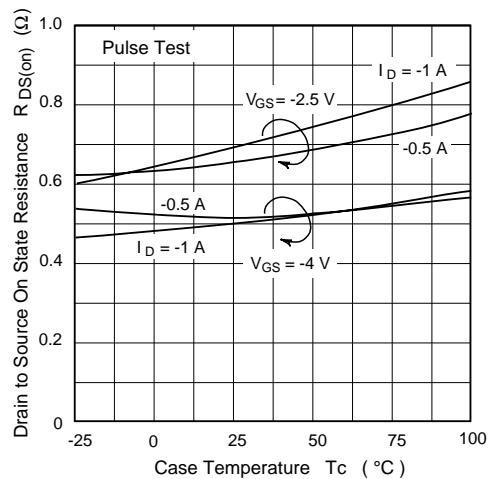
Drain to Source On State Resistance
vs. Drain Current



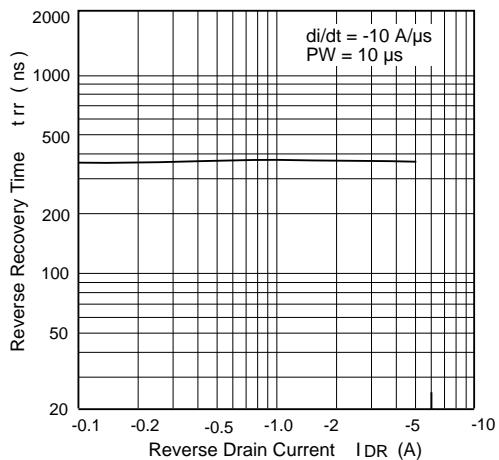
Drain to Source Saturation Voltage
vs. Gate to Source Voltage



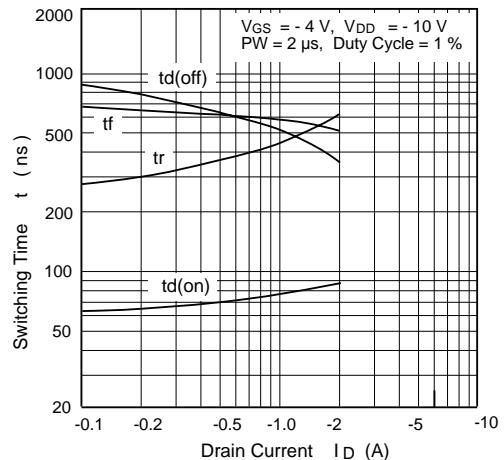
Drain to Source On State Resistance
vs. Case Temperature



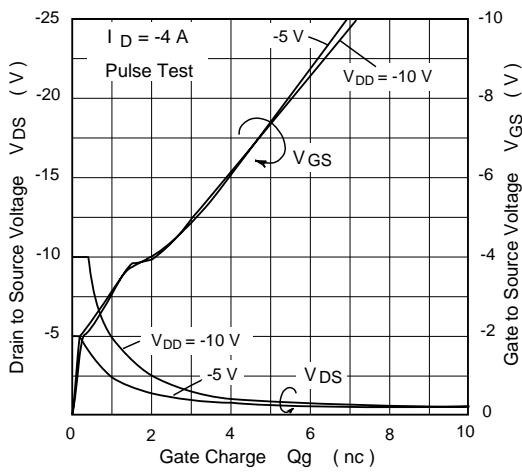
Reverse Recovery Time vs.
Reverse Drain Current



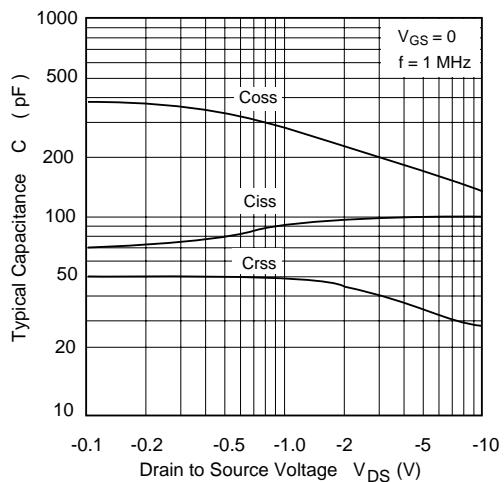
Switching Time vs. Drain Current



Dynamic Input Characteristics



Typical Capacitance vs.
Drain to Source Voltage



Reverse Drain Current vs.
Source to Drain Voltage

